

Document Title

512Kx8 bit Low Power and Low Voltage CMOS Static RAM

Revision History

<u>Revision No.</u>	<u>History</u>	<u>Draft Data</u>	<u>Remark</u>
0.0	Initial Draft	June 15, 1998	Preliminary
1.0	Finalize	April 17, 1999	Final

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512Kx8 bit Low Power and Low Voltage CMOS Static RAM

FEATURES

- Process Technology: TFT
- Organization: 512Kx8
- Power Supply Voltage
K6T4008S1C Family: 2.3~2.7V
- Low Data Retention Voltage: 2V(Min)
- Three state output and TTL Compatible
- Package Type: 32-TSOP2-400F/R
32-TSOP1-0820F, 32-TSOP1-0813.4F

GENERAL DESCRIPTION

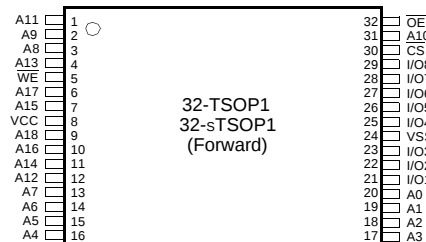
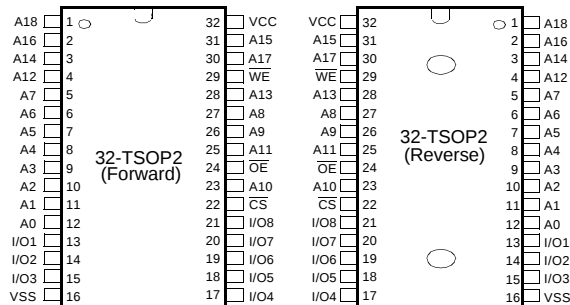
The K6T4008S1C families are fabricated by SAMSUNG's advanced CMOS process technology. The families support industrial operating temperature range and have various package type for user flexibility of system design. The families also support low data retention voltage for battery back-up operation with low data retention current.

PRODUCT FAMILY

Product Family	Operating Temperature	Vcc Range	Speed	Power Dissipation		PKG Type
				Standby (Isb1, Max)	Operating (Icc2, Max)	
K6T4008S1C-F	Industrial(-40~85°C)	2.3~2.7V	100*/120ns	15µA	16mA	32-TSOP2-F/R 32-TSOP1-F 32-sTSOP1-F

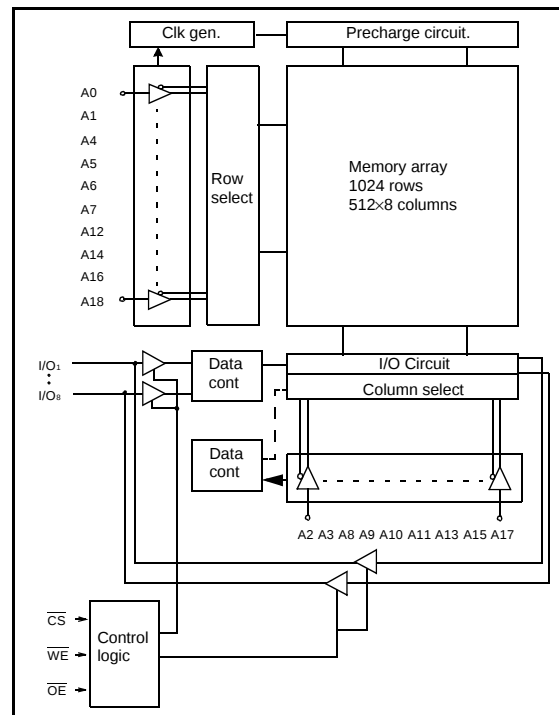
1. The parameter is measured with 30pF test load.

PIN DESCRIPTION



Name	Function	Name	Function
A0~A18	Address Inputs	Vcc	Power
$\overline{WE}$	Write Enable Input	Vss	Ground
$\overline{CS}$	Chip Select Input	I/O1~I/O8	Data Inputs/Outputs
$\overline{OE}$	Output Enable Input		

FUNCTIONAL BLOCK DIAGRAM



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PRODUCT LIST

Industrial Temp Products(-40~85°C)	
Part Name	Function
K6T4008S1C-VF10	32-TSOP2-F, 100ns, 2.5V, LL
K6T4008S1C-VF12	32-TSOP2-F, 120ns, 2.5V, LL
K6T4008S1C-MF10	32-TSOP2-R, 100ns, 2.5V, LL
K6T4008S1C-MF12	32-TSOP2-R, 120ns, 2.5V, LL
K6T4008S1C-TF10	32-TSOP1-F, 100ns, 2.5V, LL
K6T4008S1C-TF12	32-TSOP1-F, 120ns, 2.5V, LL
K6T4008S1C-YF10	32-sTSOP1-F, 100ns, 2.5V, LL
K6T4008S1C-YF12	32-sTSOP1-F, 120ns, 2.5V, LL

FUNCTIONAL DESCRIPTION

CS	OE	WE	I/O	Mode	Power
H	X ¹⁾	X ¹⁾	High-Z	Deselected	Standby
L	H	H	High-Z	Output Disabled	Active
L	L	H	Dout	Read	Active
L	X ¹⁾	L	Din	Write	Active

1. X means don't care (Must be in low or high state)

ABSOLUTE MAXIMUM RATINGS¹⁾

Item	Symbol	Ratings	Unit	Remark
Voltage on any pin relative to Vss	V _{IN} , V _{OUT}	-0.5 to V _{CC} +0.5	V	-
Voltage on Vcc supply relative to Vss	V _{CC}	-0.3 to 4.6	V	-
Power Dissipation	P _D	1.0	W	-
Storage temperature	T _{STG}	-65 to 150	°C	-
Operating Temperature	T _A	-40 to 85	°C	Industrial Product

1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation should be restricted to recommended operating condition. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS¹⁾

Item	Symbol	Product	Min	Typ	Max	Unit
Supply voltage	V _{CC}	K6T4008S1C Family	2.3	2.5	2.7	V
Ground	V _{SS}	All Family	0	0	0	V
Input high voltage	V _{IH}	All Family	2.0	-	V _{CC} +0.3 ²⁾	V
Input low voltage	V _{IL}	All Family	-0.3 ³⁾	-	0.6	V

Note:

1. T_A=-40 to 85°C, otherwise specified2. Overshoot : V_{CC}+1.0V in case of pulse width ≤ 20ns

3. Undershoot : -1.0V in case of pulse width ≤ 20ns

4. Overshoot and undershoot are sampled, not 100% tested.

CAPACITANCE¹⁾ (f=1MHz, T_A=25°C)

Item	Symbol	Test Condition	Min	Max	Unit
Input capacitance	C _{IN}	V _{IN} =0V	-	8	pF
Input/Output capacitance	C _{IO}	V _{IO} =0V	-	10	pF

1. Capacitance is sampled, not 100% tested

DC AND OPERATING CHARACTERISTICS

Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Input leakage current	I _{LI}	V _{IN} =V _{SS} to V _{CC}	-1	-	1	μA
Output leakage current	I _{LO}	$\overline{CS}=V_{IH}$ or $\overline{OE}=V_{IH}$ or $\overline{WE}=V_{IL}$ V _{IO} =V _{SS} to V _{CC}	-1	-	1	μA
Operating power supply current	I _{CC}	I _{IO} =0mA, $\overline{CS}=V_{IL}$, V _{IN} =V _{IL} or V _{IH} , read	-	-	1	mA
Average operating current	I _{CC1}	Cycle time=1μs, 100% duty, I _{IO} =0mA, $\overline{CS} \leq 0.2V$, V _{IN} ≤0.2V or V _{IN} ≥V _{CC} -0.2V	-	-	3	mA
	I _{CC2}	Cycle time=Min, 100% duty, I _{IO} =0mA, $\overline{CS}=V_{IL}$, V _{IN} =V _{IH} or V _{IL}	-	-	16	mA
Output low voltage	V _{OL}	I _{OL} =0.5mA	-	-	0.4	V
Output high voltage	V _{OH}	I _{OH} =-0.5mA	2.0	-	-	V
Standby Current(TTL)	I _{SB}	$\overline{CS}=V_{IH}$, Other inputs = V _{IL} or V _{IH}	-	-	0.3	mA
Standby Current (CMOS)	I _{SB1}	$\overline{CS} \geq V_{CC}-0.2V$, Other inputs=0~V _{CC}	-	-	15	μA

AC OPERATING CONDITIONS

TEST CONDITIONS (Test Load and Input/Output Reference)

Input pulse level : 0.4 to 2.2V

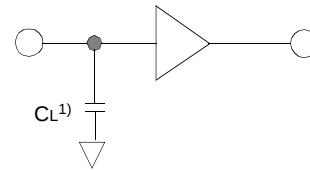
Input rising and falling time : 5ns

Input and output reference voltage : 1.1V

Output load(see right) : $C_L=100\text{pF}+1\text{TTL}$

$C_L=30\text{pF}+1\text{TTL}$

1. K6T4008S1C-10 Family



1. Including scope and jig capacitance

AC CHARACTERISTICS ($V_{CC}=2.3\sim 2.7\text{V}$, $T_A=-40$ to 85°C)

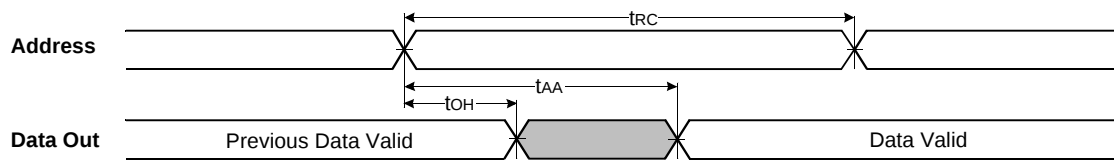
Parameter List		Symbol	Speed Bins				Units
			100ns		120ns		
			Min	Max	Min	Max	
Read	Read cycle time	trC	100	-	120	-	ns
	Address access time	tAA	-	100	-	120	ns
	Chip select to output	tCO	-	100	-	120	ns
	Output enable to valid output	tOE	-	50	-	60	ns
	Chip select to low-Z output	tLZ	10	-	10	-	ns
	Output enable to low-Z output	tOLZ	5	-	5	-	ns
	Chip disable to high-Z output	tHZ	0	30	0	35	ns
	Output disable to high-Z output	tOHZ	0	30	0	35	ns
	Output hold from address change	tOH	15	-	15	-	ns
Write	Write cycle time	tWC	100	-	120	-	ns
	Chip select to end of write	tCW	80	-	100	-	ns
	Address set-up time	tAS	0	-	0	-	ns
	Address valid to end of write	tAW	80	-	100	-	ns
	Write pulse width	tWP	70	-	80	-	ns
	Write recovery time	tWR	0	-	0	-	ns
	Write to output high-Z	tWHZ	0	30	0	35	ns
	Data to write time overlap	tdW	40	-	50	-	ns
	Data hold from write time	tdH	0	-	0	-	ns
	End write to output low-Z	tOW	5	-	5	-	ns

DATA RETENTION CHARACTERISTICS

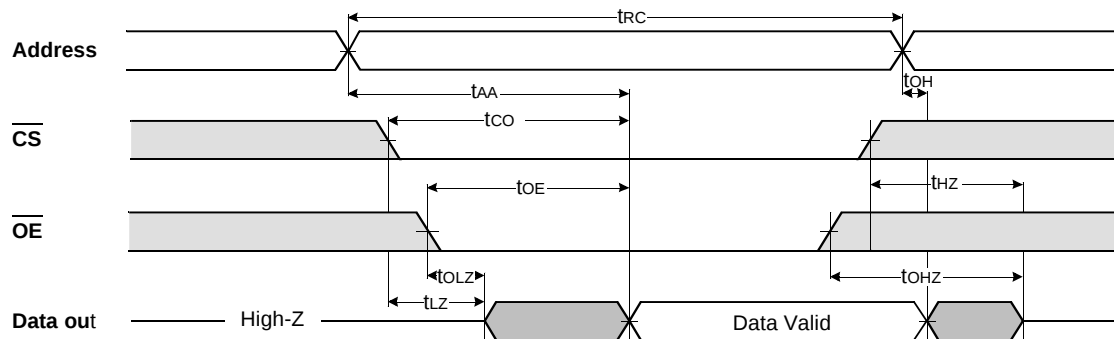
Item	Symbol	Test Condition	Min	Typ	Max	Unit
Vcc for data retention	VDR	$\overline{CS} \geq V_{CC}-0.2\text{V}$	2.0	-	3.6	V
Data retention current	IDR	$V_{CC}=2.5\text{V}$, $\overline{CS} \geq V_{CC}-0.2\text{V}$	-	0.5	15	μA
Data retention set-up time	tSDR	See data retention waveform	0	-	-	ms
Recovery time	trDR		5	-	-	

TIMMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE(1) (Address Controlled, $\overline{CS}=\overline{OE}=V_{IL}$, $\overline{WE}=V_{IH}$)



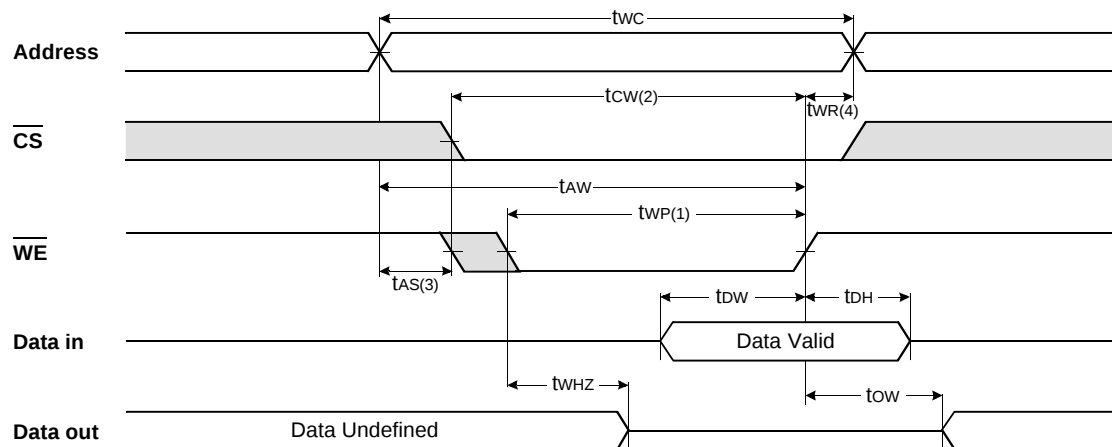
TIMING WAVEFORM OF READ CYCLE(2) ($\overline{WE}=V_{IH}$)



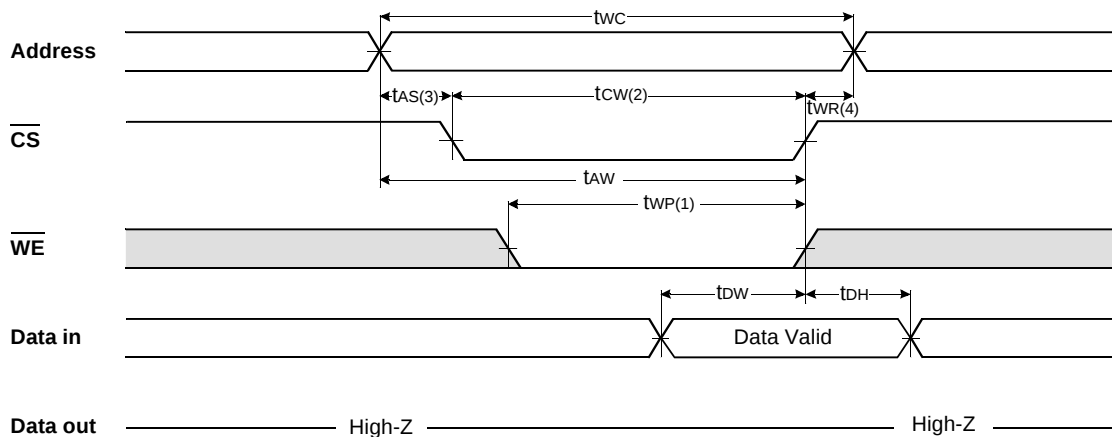
NOTES (READ CYCLE)

1. t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
2. At any given temperature and voltage condition, $t_{HZ}(\text{Max.})$ is less than $t_{LZ}(\text{Min.})$ both for a given device and from device to device interconnection.

TIMING WAVEFORM OF WRITE CYCLE(1) ($\overline{WE}$ Controlled)



TIMING WAVEFORM OF WRITE CYCLE(2) ($\overline{CS}$ Controlled)

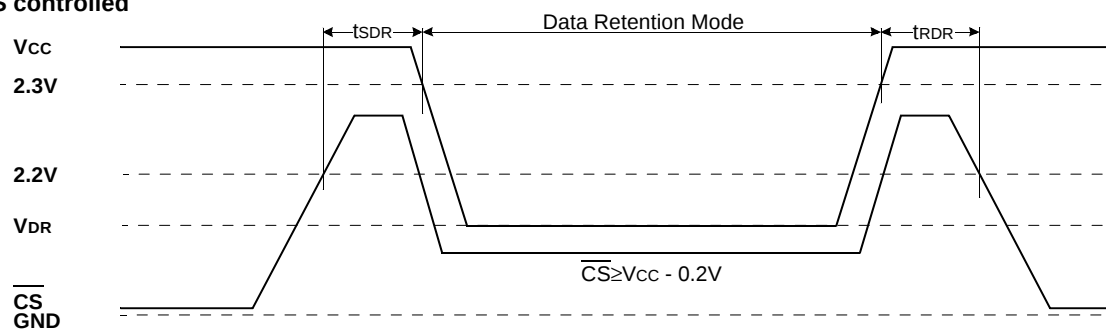


NOTES (WRITE CYCLE)

1. A write occurs during the overlap of a low $\overline{CS}$ and a low $\overline{WE}$. A write begins at the latest transition among $\overline{CS}$ going Low and $\overline{WE}$ going low : A write ends at the earliest transition among CS going high and WE going high, t_{WP} is measured from the beginning of write to the end of write.
2. t_{CW} is measured from the $\overline{CS}$ going low to end of write.
3. t_{AS} is measured from the address valid to the beginning of write.
4. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as $\overline{CS}$ or $\overline{WE}$ going high.

DATA RETENTION WAVE FORM

$\overline{CS}$ controlled



CMOS SRAM

Units: millimeters(inches)

[illegible]

Technical drawing of a rectangular component with dimensions and tolerances. The drawing includes a top view and a side view.

Top View Dimensions:

- Overall width: 13.40 ± 0.10 / 0.528 ± 0.008
- Overall height: 0.20 ± 0.10 / -0.05 / 0.006 ± 0.004 / 0.002
- Left side features: #1, #16, #32, #17
- Right side features: #1, #16, #32, #17
- Bottom left corner: 0.50 / 0.0197

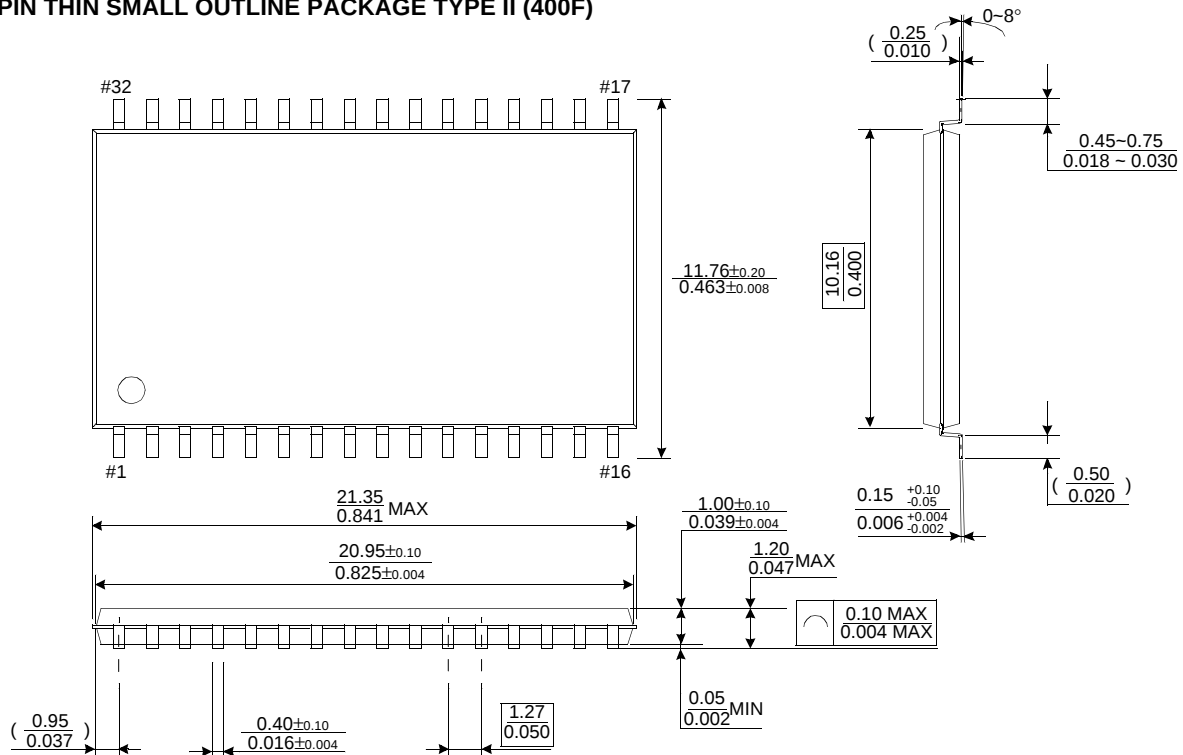
Side View Dimensions:

- Overall height: 8.40 / 0.331 MAX
- Internal height: 8.00 / 0.315
- Bottom left corner: 0.25 / 0.010 TYP
- Bottom right corner: 0.15 ± 0.10 / -0.05 / 0.006 ± 0.004 / 0.002
- Bottom center: 1.10 MAX / 0.004 MAX
- Bottom right corner: 0.05 / 0.002 MIN
- Bottom right corner: 1.20 / 0.047 MAX
- Bottom right corner: 1.00 ± 0.10 / 0.039 ± 0.004
- Bottom right corner: 0.25 / 0.010 TYP
- Bottom right corner: $0.45 - 0.75$ / $0.018 - 0.030$
- Bottom right corner: 0.50 / 0.020

PACKAGE DIMENSIONS

Units: millimeters(inches)

32 PIN THIN SMALL OUTLINE PACKAGE TYPE II (400F)



32 PIN THIN SMALL OUTLINE PACKAGE TYPE II (400R)

